

MV-3 OMNI Desktop 3D AOI Series

- Exclusive 15MP/25MP CoaXPress Camera System
- OMNI-VISION[®] 3D Digital Tri-Frequency Moiré Technology

EMIER INSPECTION

- Leading-Edge 12 Projection Blue DLP Technology
- Precision Compound Telecentric Camera Lens
- Eight Phase Color Lighting System
- 10MP/18MP SIDE-VIEWER[®] Camera System
- Programmable Z-Axis Multi-Focus System
- INTELLI-PRO[®] Automatic Programming Software
- Multi-Functional AOI-SPI Fusion Technology
- INTELLISYS[®] Industry 4.0 Intelligent Factory Automation System



MV-3 OMNI Desktop 3D AOI Series Specifications

Standard Features:

- ▶ Intel[®] Multi-Core PC, 32" Flat Screen LCD Monitor, Windows 10TM OS, HDD, Mouse & Keyboard, Network LAN Card.
- OMNI-VISION[®] Digital Tri-Frequency Moiré Technology 12 Projection Blue DLP 25mm 3D Inspection Capability.
- Semi-Automatic PCB Support System.
- Advanced Eight (8) Phase Color LED Lighting System
- Pre and Post Reflow Inspection Capability.
- > Automatic Teach Tool (ATT) Software Automatic Programming Using Centroid Data.
- Comprehensive Package Type Library Provides Simple "Drag and Drop" Component Programming.
- Local System Software: Repair Plus Software, Statistical Process Control (SPC) Software.

Options:

- 15 Mega Pixel or 25 Mega Pixel CoaXPress Top-Down Color Camera System (See Specifications).
- SIDE-VIEWER[®] Camera System Quantity (4) 10MP or 18MP CXP Side-Angle Digital Color Cameras. (See Specifications).
- > Programmable Z-Axis Multi-Focus System Provides Optimal Focus Level for Taller Devices.
- ▶ ePM-AOI CAD Import Software. ODB++ Import Module Sold Separately (Requires ePM AOI).
- > AOI-SPI Fusion Technology Provides Both AOI and SPI Capability in a Single Platform.
- > 2D Bar Code Reader Options: Gun Type and Camera Type.
- Remote PC Software Purchased Separately.
- Remote Software: Repair System Software, Statistical Process Control (SPC) Software, Off-Line Teaching Software (OLTT).
- Total Remote Management Software (TRMS) Requires Server Software for Remote PC and Client Software on All Machines.
- ▶ INTELLI-TRACK[®] Process Control Software Requires Server Software for Remote PC and Client Software on All Machines.
- SVN Multi-System Version Control Software Requires Separate PC Server.

System Specifications:

(Subject to change without prior notice)

| | PCB Inspection | on Area | | |
|---|---|---|------------------------------------|--|
| MV-3 OMNI | 50 mm x 50 mm to 450 mm x 400 mm (2.0" x 2.0" to 17.2" x 15.75") | | | |
| | Vision System | | | |
| | Vision System | | 50 50 mm v 50 50 mm (0.04" v 0.04" | |
| 15MP CoaXPress: (3,904 x 3,904 @ 120 fps) | Option 1 | Pixel Resolution: 15 um | 58.56 mm x 58.56 mm (2.31" x 2.31" | |
| 25MP CoaXPress: (5,120 x 5,120 @ 72 fps) | Option 2 | Pixel Resolution: 10 um Pixel Resolution: 7.7 um | 39.04 mm x 39.04 mm (1.54" x 1.54" | |
| 25MP COARPIESS. (5,120 x 5,120 @ 72 1ps) | Option 1 | Pixel Resolution: 7.7 um | 39.42 mm x 39.42 mm (1.55" x 1.55" | |
| | OMNI-VISION [®] Inspec | tion Technology | | |
| 3D Inspection Technology | Digital Tri-Frequency Moiré Technology - 12 Projection Blue DLP | | | |
| 2D Inspection Technology | 15MP / 25MP CoaXPress Camera System | | | |
| Maximum 3D Inspection Height | 25 mm @ ±3 um | | | |
| 2D Inspection Item | Missing Component, Wrong Component, Mis-Alignment, Skewed Component, Polarity, Tombstone, Solder Bridge, Flipped Device, Solder Ball, Etc | | | |
| 3D Inspection Item | Component Height, Position, Lifted Package, Lifted Lead, Solder Fillet, Excessive Solder, Insufficient Solder, Solder Bridge, Open Solder, Etc | | | |
| | Additional Spec | ifications | | |
| Lens Configuration | Pr | Precision Telecentric Compound Lens Design | | |
| Lighting System | | Eight Phase Color Lighting | | |
| SIDE-VIEWER® Camera System | Quantity Four - 10MP Color Side-Angle Cameras | | | |
| SIDE-VIEWER' Califera System | Quantity Four - 18MP CoaXPress Color Side-Angle Cameras | | | |
| PCB Surface Clearance | Top-Side C | ide Clearance: 45 mm / Bottom-Side Clearance: 50 mm | | |
| PCB Edge Clearance | Top-Edge C | Top-Edge Clearance: 3 mm / Bottom-Edge Clearance: 3.5 mm | | |
| Maximum PCB Warpage | | ±2 mm | | |
| Maximum PCB Weight | | Standard: 3 Kg (6.61 Lbs.) | | |
| PCB Thickness Range | Standard: 0.5 mm - 3 mm / Optional: 0.5 mm - 5 mm | | | |
| Minimum Component Inspection | 0402 Chip (mm) / 01005 Chip (in) / 0.3 Pitch (mm) | | | |
| Robot Positioning System | Precision Closed Loo | Loop AC Servo Drive, Resolution: 1 um / Repeatability: ±10 um | | |
| Power Requirements | Single Phase 2 | Single Phase 200~240V 50~60Hz; 1.1 KW, Breaker Capacity: 25 Amp | | |

| Machine Dimensions and Weight | | | |
|-------------------------------|--|-------------------|--|
| MV-3 OMNI | 975 mm L x 1,300 mm W x 790 mm H (38.4" x 51.2" x 31.1") | 200 Kg (440 lbs.) | |